

Abstract

In a wiring manufacturing process which uses conventional photolithography, most of resist and wiring material, or process gas which is necessary at the time of plasma processing, etc. is wasted. Also, since air discharging means such as a vacuum equipment is necessary, an entire apparatus grows in size, and therefore, it has been a problem that production cost increases with growing in size of a processing substrate. In this invention, applied is such means that droplets are used for resist and wiring material, and they are emitted directly to a necessary place on the substrate in a line form or a dot form, to draw a pattern. Also, applied is means which carries out a gas reaction process such as ashing and etching, under atmospheric pressure or the vicinity of atmospheric pressure.